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Dated: August 23, 2005

Signature:

Jean Bove

Ref.: 7452-105/10313554  
(PATENT)



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Shih-Ping Hsu

Application No.: 10/695,356

Filed: October 27, 2003

For: SEMICONDUCTOR PACKAGE  
SUBSTRATE HAVING CONTACT PAD  
PROTECTIVE LAYER FORMED THEREON  
AND METHOD FOR FABRICATING THE  
SAME

Confirmation No.: 6002

Group Art Unit: 2813

Examiner: Nema O. Berezny

*ENTER  
With RCE  
FILED 9/12/05  
C. Molina*

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Mail Stop: AF

Dear Sir:

In response to the Office Action mailed April 12, 2005, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.